

# TD1F THRU TD10F-HAF

**Surface Mount Glass passivated Bridge Rectifier**  
**Reverse Voltage - 100 to 1000 V**  
**Forward Current - 1 A**

## Features

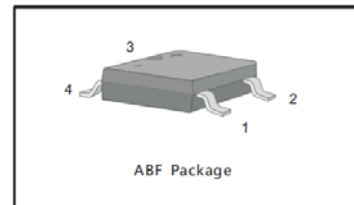
- Glass passivated chip
- High Surge Current Capability
- Designed for Surface Mount Application
- Halogen and Antimony Free(HAF), RoHS compliant

## Mechanical Data

- **Package:** ABF
- **Terminals:** Solderable per MIL-STD-750, Method 2026

PINNING

PIN	DESCRIPTION
1	Input Pin ( ~ )
2	Input Pin ( ~ )
3	Output Anode ( + )
4	Output Cathode ( - )



## Maximum Ratings and Electrical characteristics

Single-phase, half-wave, 60 Hz, resistive or inductive load rating at 25°C, unless otherwise specified, for capacitive load, derate current by 20 %.

Parameter	Symbols	TD1F	TD2F	TD4F	TD6F	TD8F	TD10F	Units
	Marking	10F1	10F2	10F4	10F6	10F8	10F10	-
Maximum Repetitive Peak Reverse Voltage	$V_{RRM}$	100	200	400	600	800	1000	V
Maximum RMS voltage	$V_{RMS}$	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	$V_{DC}$	100	200	400	600	800	1000	V
Average Forward Current at $T_a = 50^\circ\text{C}$	$I_{F(AV)}$	1						A
Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load(JEDEC Method)	$I_{FSM}$	35						A
Maximum Instantaneous Forward Voltage at 1 A	$V_F$	1.1						V
Maximum DC Reverse Current at Rated DC Blocking Voltage	$I_R$	5 50						$\mu\text{A}$
Typical Junction Capacitance <sup>1)</sup>	$C_j$	13						pF
Typical Thermal Resistance <sup>2)</sup>	$R_{\theta JA}$ $R_{\theta JL}$	80 20						$^\circ\text{C/W}$
Operating and Storage Temperature Range	$T_j, T_{stg}$	- 55 to + 150						$^\circ\text{C}$

<sup>1)</sup> Measured at 1 MHz and applied reverse voltage of 4 V D.C.

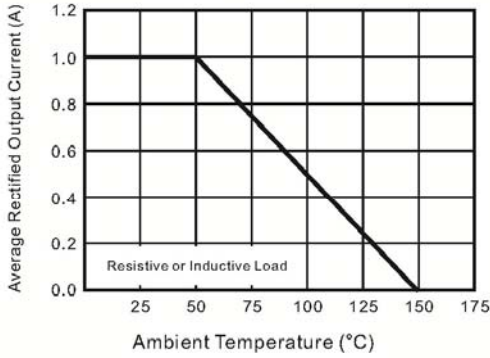
<sup>2)</sup> Mounted on glass epoxy PC board with 4 X ( 5 X 5 mm<sup>2</sup> ) copper pad.

**TOP DYNAMIC**

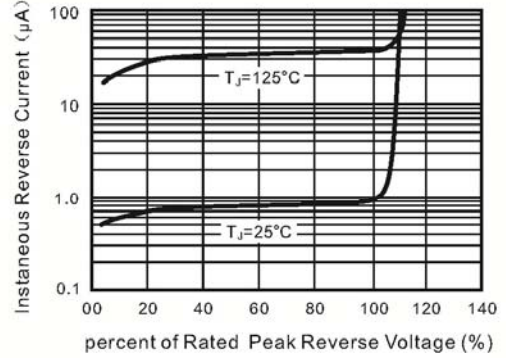


# TD1F THRU TD10F-HAF

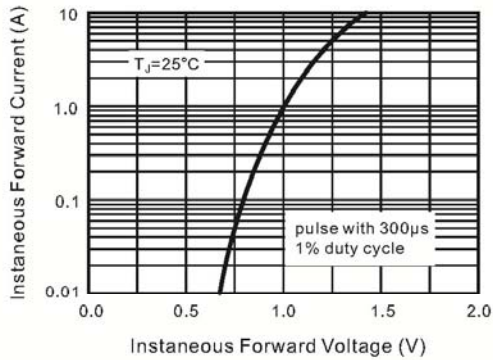
**Average Rectified Output Current Derating Curve**



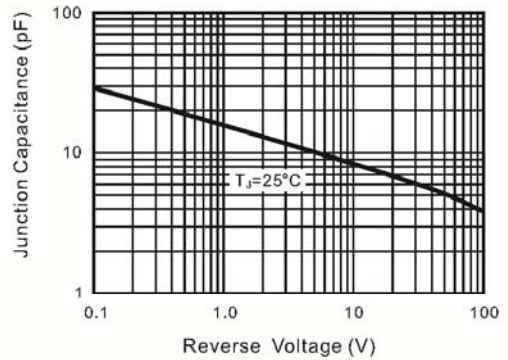
**Typical Reverse Characteristics**



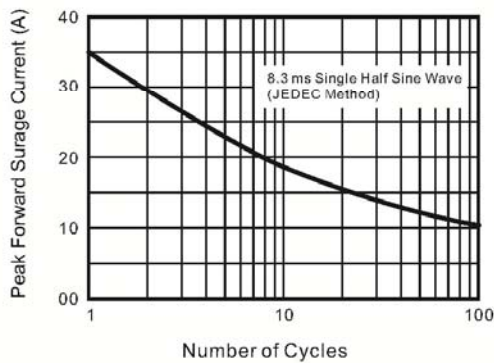
**Typical Instantaneous Forward Characteristics**



**Typical Junction Capacitance**



**Maximum Non-Repetitive Peak Forward Surge Current**



**TOP DYNAMIC**

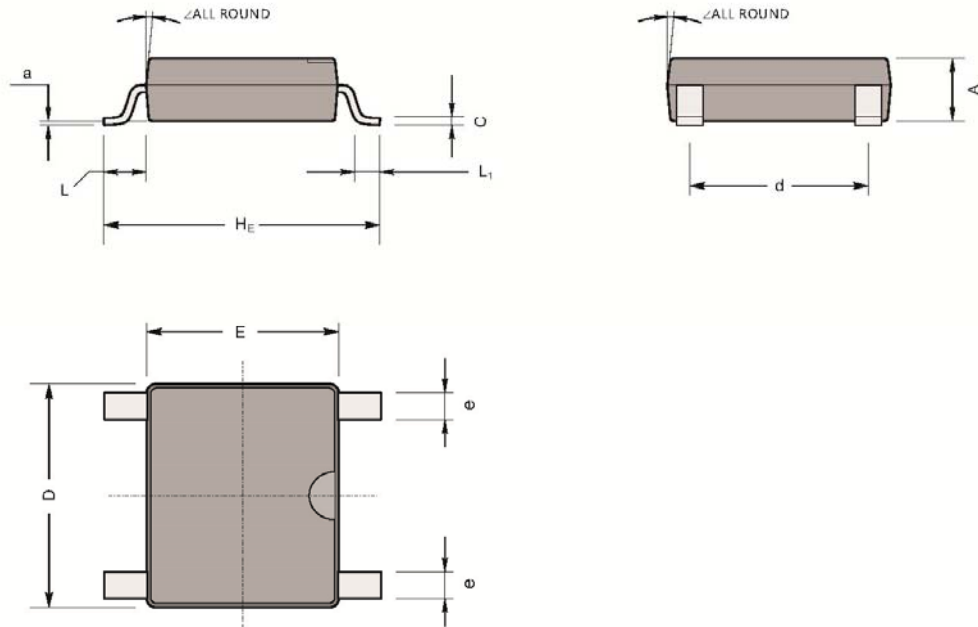


# TD1F THRU TD10F-HAF

## PACKAGE OUTLINE

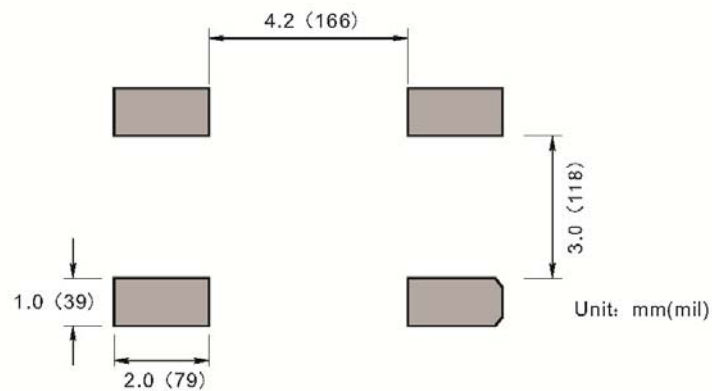
ABF

Plastic surface mounted package; 4 leads



UNIT	A	C	D	E	HE	d	e	L	L1	a	∠
mm	1.2	0.22	5.2	4.5	6.4	4.2	0.7	0.95	0.6	0.1	7°
	1	0.15	4.9	4.2	6	3.6	0.5				

## Recommended Soldering Footprint



**TOP DYNAMIC**

